

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1384in#pbf

(Engineering Calculation)

PDIP

(printed on: 2020-07-11 21:35:53)

TOTAL MASS (g) : 1.202708

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003860 | 1000000 | 3209.42358398 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.345150 | 975000 | 286977.3125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.008496 | 24000 | 7064.05761719 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000106 | 300 | 88.1344223022 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000248 | 700 | 206.201293945 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.354000 | 1000000 | 294335.71875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.027934 | 1000000 | 23226.1445312 | | |
| | | External Plating Total: | | | | 0.027934 | 1000000 | 23226.1445312 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.002832 | 1000000 | 2354.68579102 | | |
| Internal Plating Total: | | | | 0.002832 | 1000000 | 2354.68579102 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001080 | 750000 | 897.973388672 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000360 | 250000 | 299.324462891 | | |
| Die Attach Total: | | | | 0.001440 | 1000000 | 1197.29785156 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.194880 | 240000 | 162034.296875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.008120 | 10000 | 6751.4296875 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.584640 | 720000 | 486102.9375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.024360 | 30000 | 20254.2871094 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.812000 | 1000000 | 675142.9375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000642 | 1000000 | 533.795288086 | | |
| | | | | | TOTAL MASS (g) : | 1.202708 | | |